Variant: 001 Generated: 5/16/2018 2:13:48 PM TID #: PMP15039

## PMP15039 REV E1 Bill of Materials



Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB	1		PMP15039	Any	Printed Circuit Board	
2	C1	1	4.7uF	JMK107BB7475MA-T	Taiyo Yuden	CAP, CERM, 4.7 uF, 6.3 V, +/- 10%, X7R, 0603	0603
3	C2	1	22uF	GRM21BZ71A226ME15L	MuRata	CAP, CERM, 22 uF, 10 V, +/- 20%, X7R, 0805	0805
4	C3, C4	2	0.047uF	CGA3E3X7S2A473K080AB	TDK	CAP, CERM, 0.047 µF, 100 V,+/- 10%, X7S, AEC-Q200 Grade 1, 0603	0603
5	C5	1	4.7uF	CGA6M3X7S2A475K200AB	TDK	CAP, CERM, 4.7 µF, 100 V, +/- 10%, X7S, AEC-Q200 Grade 1, 1210	1210
6	C6	1	10uF	GRM21BR71A106ME51L	MuRata	CAP, CERM, 10 uF, 10 V, +/- 20%, X7R, 0805	0805
7	C7	1	120pF	GRM1555C1H121FA01D	MuRata	CAP, CERM, 120 pF, 50 V, +/- 1%, C0G/NP0, 0402	0402
8	C8	1	0.1uF	GRM155R71E104KE14D	MuRata	CAP, CERM, 0.1 uF, 25 V, +/- 10%, X7R, 0402	0402
9	C9	1	1uF	C1005X7S1A105K050BC	TDK	CAP, CERM, 1 uF, 10 V, +/- 10%, X7S, 0402	0402
10	C10	1	20pF	GRM1555C1E200JA01D	MuRata	CAP, CERM, 20 pF, 25 V,+/- 5%, C0G/NP0, 0402	0402
11	L1	1	10uH	74438357100	Wurth Elektronik	Inductor, Shielded, Metal Composite, 10 µH, 2.7 A, 0.11 ohm, SMD	4.1x4.1mm
12	L2	1	1.5uH	XFL3012-152MEB	Coilcraft	Inductor, Shielded, Composite, 1.5 uH, 2.2 A, 0.06 ohm, SMD	3x1.2x3mm
13	R1	1	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
14	R2	1	150k	ERJ-2RKF1503X	Panasonic	RES, 150 k, 1%, 0.1 W, AEC-Q200 Grade 0, 0402	0402
15	R3, R4, R5, R6	4	100k	CRCW0402100KFKED	Vishay-Dale	RES, 100 k, 1%, 0.063 W, 0402	0402
16	R7	1	24.9k	CRCW040224K9FKED	Vishay-Dale	RES, 24.9 k, 1%, 0.063 W, 0402	0402
17	TP1, TP2, TP3, TP4, TP5, TP6, TP7	7		5015	Keystone	Test Point, Miniature, SMT	Testpoint_Keystone_ Miniature
18	U1	1		LMR36006BRNXR	Texas Instruments	65-V 0.6-A Synchronous Step-Down Converter, RNX0012B (VQFN-HR- 12)	RNX0012B
19	U2	1		TPS62821DLC	Texas Instruments	2.5-V to 5.5-V, 1-, 2-, 3-A Step-Down Converter with DCS-Control, DLC0008A (SON-HR-8)	DLC0008A

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